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(54) **MICRO LED STRUCTURE AND MICRO LED PANEL**

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(57) **ABSTRACT**

Micro LED structures and micro LED panels using the same are disclosed. A disclosed micro LED includes an IC back plane, and a stack of mesa structures comprising at least a first and a second mesa structures. The first mesa structure comprises: a first light-emitting layer, a first connecting layer formed on the first light-emitting layer, and a first conductive bonding layer formed under the first light-emitting layer and electrically connecting the first light-emitting layer to the IC back plane. The second mesa structure is formed on the first mesa structure and comprises: a second light-emitting layer, a second connecting layer formed on the second light-emitting layer, a second conductive bonding layer formed under the second light-emitting layer, and a third connecting layer formed under the second conductive bonding layer and electrically connected to the second light-emitting layer via the second conductive bonding layer.

